

Part Number: **DDZ9xxxT-(p)-F**
Weight (mg): 1.44

p = package designator
See Data Sheet

xxx = 689, 690, 691, 692, 693, 694, 695, 696, 697, 698, 699, 700, 701, 702, 703, 705, 707, 708, 709, 711, 712, 713, 714, 715, 716, 717

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.06	0.04	1000000	30627
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	40.45	0.58	576500	233218
		Ni	7440-02-0	41.00%			410000	165862
		Mn	7439-96-5	0.60%			6000	2427
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	405
		Co	7440-48-4	0.50%			5000	2023
		Si	7440-21-3	0.15%			1500	607
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.52	0.02	1000000	15209
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.44	0.01	1000000	4375
Encapsulation	CEL-1702HF-9	SiO2	60676-86-0	87.30%	53.20	0.77	873000	464420
		Epoxy Resin	29690-82-2	5.00%			50000	26599
		Phenol Resin	26834-02-6	5.00%			50000	26599
		Aromatic poly-phosphate	----	2.50%			25000	13300
		C	1333-86-4	0.20%			2000	1064
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.33	0.02	1000000	13265
Total					100.00	1.44		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)